June 2022

Circuit Foil, participated in the EIPC (European Institute for the PCB Community) conference in Örebro, southern Sweden, from June 14 to 15.

At this conference, more than 100 experts from manufacturers of materials, parts, and equipment suppliers PCB (Printed Circuit Board) electronics manufacturers gathered to exchange PCB-related technologies.

Dr. Sebastian Depaifve, CFL's representative speaker, introduced the next-generation "Ultra Flat ED Copper Foil" that can be applied to 5G and 6G mobile communication through high-speed and high-frequency signal transmission.

Circuit Foil can reply to high quality requirements thanks to state-of-the-art research & developments, especially for applications requiring high level of signal integrity.

The presentation focused on the ED copper foils factors influencing the insertion loss.





Source 1: Alun Morgan, EIPC President